

Docket No. P0298US-7

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/666,399  
Applicants : LEUNG et al.  
Filed : September 18, 2003  
TC/A.U. : 2814  
Examiner : Thao X. Le  
Docket No. : P0298US-7  
Title: MOLDED CHIP FABRICATION AND APPARATUS


Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

NOTIFICATION OF FILING OF A CONTINUATION APPLICATION

Notification is hereby being made of the filing of a continuation application, on July 21, 2009, under application No. 12/506,989.

Respectfully submitted,

Dated: 7/24/09

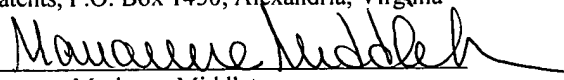
  
Jaye G. Heybl  
Registration No. 42,661  
Attorney for Applicants

KOPPEL, PATRICK, HEYBL & DAWSON  
2815 Townsgate Road, Suite 215  
Westlake Village, California 91361  
(805) 373-0060  
M/J9-P0298US-7Notice

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service via First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

7/24/09  
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Marianne Middleton